ASSP

Dual Serial Input PLL Frequency Synthesizer

MB15F74UL

■ DESCRIPTION

The Fujitsu MB15F74UL is a serial input Phase Locked Loop (PLL) frequency synthesizer with a 4000 MHz and a 2000 MHz prescalers. A 64/65 or a 128/129 for the 4000 MHz prescaler, and a 32/33 or a 64/65 for the 2000 MHz prescaler can be selected for the prescaler that enables pulse swallow operation.

The BiCMOS process is used, as a result a supply current is typically 9.0 mA at 3.0 V. The supply voltage range is from 2.7 V to 3.6 V. A refined charge pump supplies well-balanced output current with 1.5 mA and 6 mA selectable by serial date. The pin assignments are the same as MB15F78UL. Fast locking is achieved for adopting the new circuit.

The new package (BCC20) decreases a mount area of MB15F74UL more than 30% comparing with the former BCC16 (for dual PLL) .

■ FEATURES

• High frequency operation : RF synthesizer : 4000 MHz Max

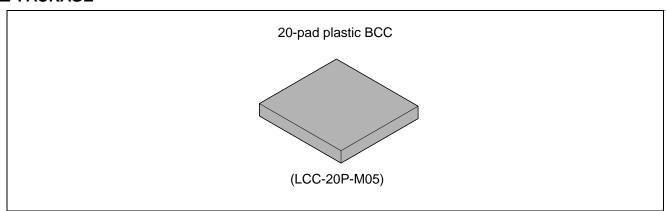
: IF synthesizer : 2000 MHz Max

Low power supply voltage : Vcc = 2.7 to 3.6 V
 Ultra low power supply current : Icc = 9.0 mA Typ

 $(V_{CC} = V_p = 3.0 \text{ V}, \text{ Ta} = +25 ^{\circ}\text{C}, \text{ SW}_{IF} = \text{SW}_{RF} = 0 \text{ in IF/RF locking state})$

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■ PACKAGE





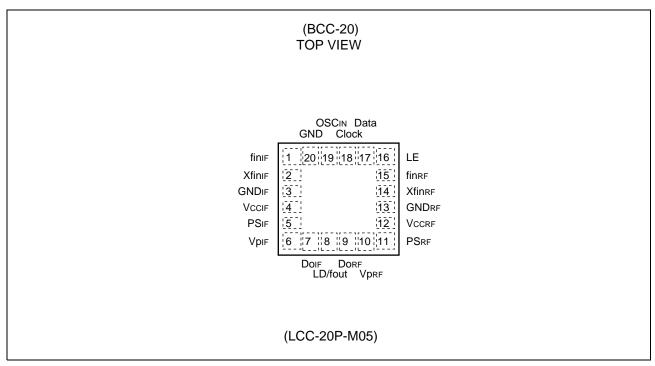
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• Direct power saving function : Power supply current in power saving mode

Typ 0.1
$$\mu$$
A (Vcc = Vp = 3.0 V, Ta = +25 °C)
Max 10 μ A (Vcc = Vp = 3.0 V)

- Software selectable charge pump current : 1.5 mA/6.0 mA Typ
- Dual modulus prescaler: 4000 MHz prescaler (64/65 or128/129) /2000 MHz prescaler (32/33 or 64/65)
- 23 bit shift register
- Serial input binary 14-bit programmable reference divider : R = 3 to 16,383
- Serial input programmable divider consisting of:
 - Binary 7-bit swallow counter: 0 to 127
 - Binary 11-bit programmable counter: 3 to 2,047
- Built-in high-speed tuning, low-noise phase comparator, current-switching type constant current circuit
- · On-chip phase control for phase comparator
- On-chip phase comparator for fast lock and low noise
- · Built-in digital locking detector circuit to detect PLL locking and unlocking
- Operating temperature : Ta = $-40 \, ^{\circ}\text{C}$ to $+85 \, ^{\circ}\text{C}$

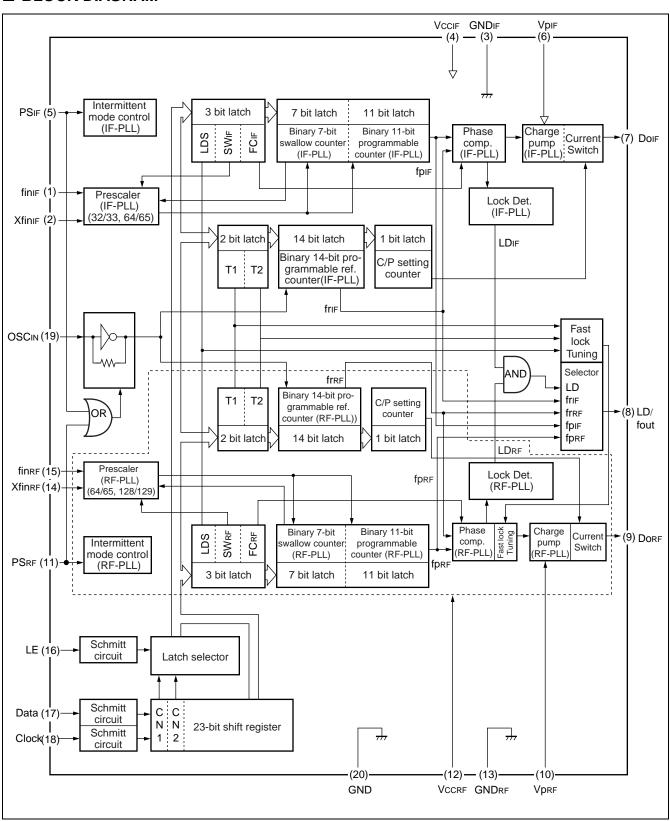
■ PIN ASSIGNMENTS



■ PIN DESCRIPTION

Pin no.	Pin name	I/O	Descriptions
1	finı⊧	I	Prescaler input pin for the IF-PLL. Connection to an external VCO should be AC coupling.
2	XfinıF	I	Prescaler complimentary input for the IF-PLL section. This pin should be grounded via a capacitor.
3	GND _{IF}		Ground pin for the IF-PLL section.
4	Vccif		Power supply voltage input pin for the IF-PLL section (except for the charge pump circuit), the shift register and the oscillator input buffer.
5	PSIF	I	Power saving mode control pin for the IF-PLL section. This pin must be set at "L" when the power supply is started up. (Open is prohibited.) $PS_{\text{IF}} = \text{"H"}; \text{ Normal mode/PS}_{\text{IF}} = \text{"L"}; \text{ Power saving mode}$
6	VpiF		Power supply voltage input pin for the IF-PLL charge pump.
7	Doif	0	Charge pump output for the IF-PLL section.
8	LD/fout	0	Lock detect signal output (LD) /phase comparator monitoring output (fout) pin. The output signal is selected by LDS bit in a serial data. LDS bit = "H"; outputs fout signal/LDS bit = "L"; outputs LD signal
9	Dorf	0	Charge pump output for the RF-PLL section.
10	Vprf		Power supply voltage input pin for the RF-PLL charge pump.
11	PS _{RF}	I	Power saving mode control for the RF-PLL section. This pin must be set at "L" when the power supply is started up. (Open is prohibited.) $PS_{RF} = "H"$; Normal mode/ $PS_{RF} = "L"$; Power saving mode
12	Vccrf		Power supply voltage input pin for the RF-PLL section (except for the charge pump circuit)
13	GNDRF		Ground pin for the RF-PLL section
14	Xfin _{RF}	I	Prescaler complimentary input pin for the RF-PLL section. This pin should be grounded via a capacitor.
15	fin _{RF}	I	Prescaler input pin for the RF-PLL. Connection to an external VCO should be via AC coupling.
16	LE	I	Load enable signal input pin (with the schmitt trigger circuit) When LE is set "H", data in the shift register is transferred to the corresponding latch according to the control bit in a serial data.
17	Data	I	Serial data input pin (with the schmitt trigger circuit) Data is transferred to the corresponding latch (IF-ref. counter, IF-prog. counter, RF-ref. counter, RF-prog. counter) according to the control bit in a serial data.
18	Clock	I	Clock input pin for the 23-bit shift register (with the schmitt trigger circuit) One bit data is shifted into the shift register on a rising edge of the clock.
19	OSCIN	I	The programmable reference divider input pin. TCXO should be connected with an AC coupling capacitor.
20	GND	_	Ground pin for OSC input buffer and the shift register circuit.

■ BLOCK DIAGRAM



■ ABSOLUTE MAXIMUM RATINGS

Parameter		Symbol	Rat	ting	Unit
		Symbol	Min		Offic
Davida		Vcc	-0.5	4.0	V
Power supply voltage	Power supply voltage		Vcc	4.0	V
Input voltage		Vı	-0.5	Vcc + 0.5	V
Output voltage	LD/fout	Vo	GND	Vcc	V
Output voltage	Doif, Dorf	V _{DO}	GND	Vp	V
Storage temperature		Tstg	-55	+125	°C

WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

■ RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol		Value		Unit	Pomarks	
Parameter	Symbol	Min	Тур	Max	Onit	Remarks VCCRF = VCCIF	
Dower cumply voltage	Vcc	2.7	3.0	3.6	V	Vccrf = Vccif	
Power supply voltage	Vp	Vcc	3.0	3.6	V		
Input voltage	Vı	GND	_	Vcc	V		
Operating temperature	Та	-40	_	+85	°C		

Note: • Vccrf, Vprf, Vccif and Vpif must supply equal voltage.

Even if either RF-PLL or IF-PLL is not used, power must be supplied to Vccre, Vpre, Vccre and Vpre to keep them equal.

It is recommended that the non-use PLL is controlled by power saving function.

- Although this device contains an anti-static element to prevent electrostatic breakdown and the circuitry has been improved in electrostatic protection, observe the following precautions when handling the device.
 - When storing and transporting the device, put it in a conductive case.
 - Before handling the device, confirm the (jigs and) tools to be used have been uncharged (grounded) as well as yourself. Use a conductive sheet on working bench.
 - Before fitting the device into or removing it from the socket, turn the power supply off.
 - When handling (such as transporting) the device mounted board, protect the leads with a conductive sheet.

WARNING: The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated within these ranges.

> Always use semiconductor devices within their recommended operating condition ranges. Operation outside these ranges may adversely affect reliability and could result in device failure.

> No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their FUJITSU representatives beforehand.

■ ELECTRICAL CHARACTERISTICS

 $(Vcc = 2.7 \text{ V to } 3.6 \text{ V}, \text{ Ta} = -40 \,^{\circ}\text{C to } +85 \,^{\circ}\text{C})$

Parameter		Symbol	Condition	Value			Unit
Parameter		Symbol	Condition	Min	Тур	Max	Unit
Power supply current		Iccif *1	finif = 2000 MHz Vccif = Vpif = 3.0 V	2.1	2.5	3.2	mA
r ower supply current		Iccrf *1	finrf = 2500 MHz Vccrf = Vprf = 3.0 V	5.7	6.5	8.4	mA
Power saving current		I PSIF	PS _{IF} = PS _{RF} = "L"	_	0.1 *2	10	μΑ
Fower saving current		I PSRF	PS _{IF} = PS _{RF} = "L"	_	0.1 *2	10	μΑ
	fin _{IF} *3	finı⊧	IF PLL	200		2000	MHz
Operating frequency	fin _{RF} *3	fin _{RF}	RF PLL	2000		4000	MHz
	OSCIN	fosc	_	3	_	40	MHz
Input sensitivity	finıғ	Pfinif	IF PLL, 50 Ω system	-15		+2	dBm
input sensitivity	finrf	Pfinre	RF PLL, 50 Ω system	-10	_	+2	dBm
Input available voltage	OSCIN	Vosc	_	0.5	_	Vcc	V _P P
"H" level input voltage	Data LE	VIH	Schmitt trigger input	0.7 Vcc + 0.4	_	_	V
"L" level input voltage	Clock	VıL	Schmitt trigger input	_	_	0.3 Vcc - 0.4	V
"H" level input voltage	PSIF	ViH	_	0.7 Vcc	_	_	V
"L" level input voltage	PSRF	VIL	_	_	_	0.3 Vcc	V
"H" level input current	Data LE	I _{IH} *4	_	-1.0	_	+1.0	μΑ
"L" level input current	Clock PS	Iı∟* ⁴	_	-1.0	_	+1.0	μА
"H" level input current	OSCIN	Іін	_	0		+100	μΑ
"L" level input current	USCIN	I _{IL} *4	_	-100	_	0	μΑ
"H" level output voltage	LD/	Vон	Vcc = Vp = 3.0 V, IoH = -1 mA	Vcc - 0.4	_	_	V
"L" level output voltage	fout	Vol	Vcc = Vp = 3.0 V, IoL = 1 mA	_	_	0.4	V
"H" level output voltage	Doir	V _{DOH}	$V_{CC} = V_p = 3.0 \text{ V}, I_{DOH} = -0.5 \text{ mA}$	Vp - 0.4	_	_	V
"L" level output voltage	Dorf	V _{DOL}	Vcc = Vp = 3.0 V, Idol = 0.5 mA	_		0.4	V
High impedance cutoff current	Doif Dorf	loff	$\begin{aligned} &\text{V}_{\text{CC}} = \text{Vp} = 3.0 \text{ V} \\ &\text{V}_{\text{OFF}} = 0.5 \text{ V to Vp} - 0.5 \text{ V} \end{aligned}$	_		2.5	nA
"H" level output current	LD/	І он *4	Vcc = Vp = 3.0 V	_		-1.0	mA
"L" level output current	fout	lol	Vcc = Vp = 3.0 V	1.0	_	_	mA

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 $(Vcc = 2.7 \text{ V to } 3.6 \text{ V}, Ta = -40 ^{\circ}\text{C to } +85 ^{\circ}\text{C})$

Paramete	ar.	Symbol	Condition	on	Value			Unit
i didilietei		Symbol	Conditi	OII	Min	Тур	Max	Oilit
"H" level output current	Doif *8	I DOH *4	$V_{CC} = V_{p} = 3.0 \text{ V},$ $V_{DOH} = V_{p} / 2,$	CS bit = "H"	-8.2	-6.0	-4.1	mA
	Dorf	IDOH	Ta = +25 °C	CS bit = "L"	-2.2	-1.5	-0.8	mA
"L" level output	Doif *8	IDOL	$V_{CC} = V_p = 3.0 \text{ V},$ $V_{DOL} = V_p / 2,$	CS bit = "H"	4.1	6.0	8.2	mA
current	Dorf	IDOL	Ta = $+25$ °C	CS bit = "L"	0.8	1.5	2.2	mA
	IDOL/IDOH	I DOMТ *5	V _{DO} = Vp / 2	•	_	3	10	%
Charge pump	vs V _{DO}	IDOVD *6	$0.5 \text{ V} \le \text{V}_{DO} \le \text{Vp} - 0.5 \text{ V}$ — 10		10	15	%	
current rate	vs Ta	IDOTA *7	-40 °C \leq Ta \leq 85 °C $V_{DO} = Vp / 2$		_	5	10	%

^{*1 :} Conditions ; fosc = 12.8 MHz, Ta = \pm 25 °C, SW = "L" in locking state.

*3 : AC coupling. 1000 pF capacitor is connected under the condition of Min operating frequency.

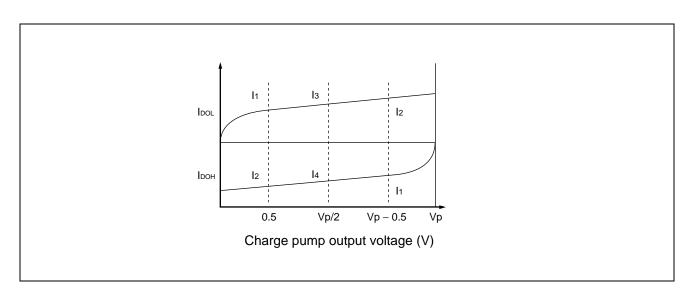
*4 : The symbol "-" (minus) means the direction of current flow.

*5 : Vcc = Vp = 3.0 V, $Ta = +25 \, ^{\circ}\text{C} \left(||I_3| - |I_4|| \right) / [(|I_3| + |I_4|) / 2] \times 100 \, (\%)$

*6 : Vcc = Vp = 3.0 V, Ta = +25 °C [(||I₂| - |I₁||) / 2] / [(|I₁| + |I₂|) / 2] × 100 (%) (Applied to both loot and looн)

*7 : $V_{CC} = V_{P} = 3.0 \text{ V}$, [||IDO (+85 °C) | - |IDO (-40 °C) || / 2] / [|IDO (+85 °C) | + |IDO (-40 °C) | / 2] × 100 (%) (Applied to both IDOL and IDOH)

*8 : When Charge pump current is measured, set LDS = "L", T1 = "L" and T2 = "H".



^{*2 :} $V_{CCIF} = V_{PIF} = V_{CCRF} = V_{PRF} = 3.0 \text{ V}$, fosc = 12.8 MHz, Ta = +25 °C, in power saving mode. PS_{IF} = PS_{RF} = GND V_{IH} = V_{CC}, V_{IL} = GND (at CLK, Data, LE)

■ FUNCTIONAL DESCRIPTION

1. Pulse swallow function

 $fvco = [(P \times N) + A] \times fosc \div R$

fvco: Output frequency of external voltage controlled oscillator (VCO)

P : Preset divide ratio of dual modulus prescaler (32 or 64 for IF-PLL, 64or 128 for RF-PLL)

N : Preset divide ratio of binary 11-bit programmable counter (3 to 2,047) A : Preset divide ratio of binary 7-bit swallow counter ($0 \le A \le 127$, A < N)

fosc: Reference oscillation frequency (OSC_{IN} input frequency)

R : Preset divide ratio of binary 14-bit programmable reference counter (3 to 16,383)

2. Serial Data Input

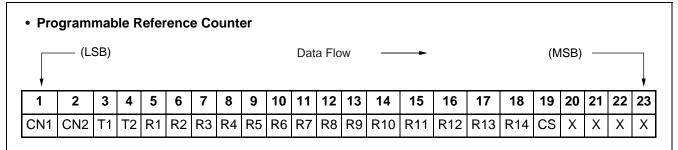
The serial data is entered using three pins, Data pin, Clock pin, and LE pin. Programmable dividers of IF/RF-PLL sections, programmable reference dividers of IF/RF-PLL sections are controlled individually.

The serial data of binary data is entered through Data pin.

On rising edge of Clock, one bit of the serial data is transferred into the shift register. On a rising edge of load enable signal, the data stored in the shift register is transferred to one of latches depending upon the control bit data setting.

	The programmable reference counter for the IF-PLL	The programmable reference counter for the RF-PLL	The programmable counter and the swallow counter for the IF-PLL	The programmable counter and the swallow counter for the RF-PLL	
CN1	0	1	0	1	
CN2	0	0	1	1	

(1) Shift Register Configuration



CS : Charge pump current select bit

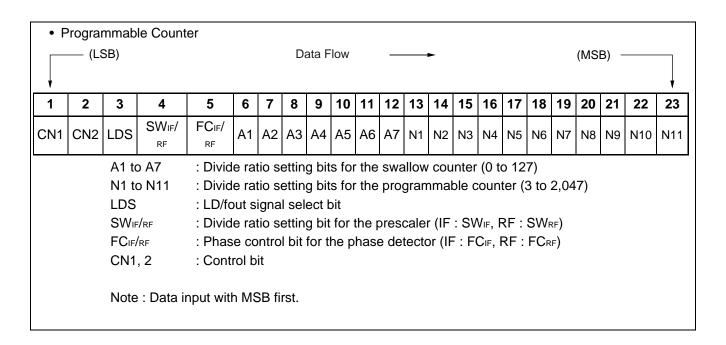
R1 to R14 : Divide ratio setting bits for the programmable reference counter (3 to 16,383)

T1, 2 : LD/fout output setting bit

CN1, 2 : Control bit

X : Dummy bits (Set "0" or "1")

Note: Data input with MSB first.



(2) Data setting

• Binary 14-bit Programmable Reference Counter Data Setting

Divide ratio	R14	R13	R12	R11	R10	R9	R8	R7	R6	R5	R4	R3	R2	R1
3	0	0	0	0	0	0	0	0	0	0	0	0	1	1
4	0	0	0	0	0	0	0	0	0	0	0	1	0	0
•	•	•	•	•	•	•	•	•	•	•	•	•	•	•
•	•	•	•	•	•	•	•	•	•	•	•	•	•	•
16383	1	1	1	1	1	1	1	1	1	1	1	1	1	1

Note: Divide ratio less than 3 is prohibited.

• Binary 11-bit Programmable Counter Data Setting

Divide ratio	N11	N10	N9	N8	N7	N6	N5	N4	N3	N2	N1
3	0	0	0	0	0	0	0	0	0	1	1
4	0	0	0	0	0	0	0	0	1	0	0
•	•	•	•	•	•	•	•	•	•	•	•
•	•	•	•	•	•	•	•	•	•	•	•
2047	1	1	1	1	1	1	1	1	1	1	1

Note: Divide ratio less than 3 is prohibited

• Binary 7-bit Swallow Counter Data Setting

Divide ratio	A7	A6	A5	A4	А3	A2	A1
0	0	0	0	0	0	0	0
1	0	0	0	0	0	0	1
•	•	•	•	•	•	•	•
•	•	•	•	•	•	•	•
•	•	•	•	•	•	•	•
127	1	1	1	1	1	1	1

• Prescaler Data Setting

Divide ratio	SW = "H"	SW = "L"
Prescaler divide ratio IF-PLL	32/33	64/65
Prescaler divide ratio RF-PLL	64/65	128/129

• Charge Pump Current Setting

Current value	CS
±6.0 mA	1
±1.5 mA	0

• LD/fout output Selectable Bit Setting

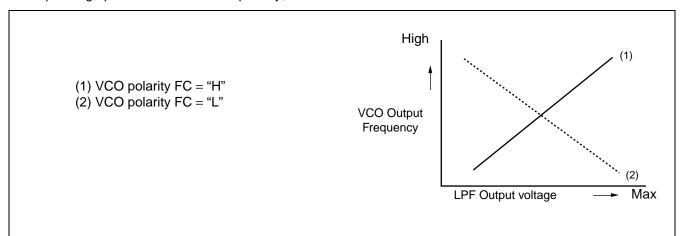
LD/fout	pin state	LDS	T1	T2
		0	0	0
LD o	utput	0	1	0
			1	1
	fr _{IF}	1	0	0
fout	fr _{RF}	1	1	0
output	fpıғ	1	0	1
	fprf	1	1	1

Phase Comparator Phase Switching Data Setting

Phase comparator input	FCif, RF = "H"	FCif, RF = "L"
	Doif, RF	Doif, RF
fr > fp	Н	L
fr < fp	L	Н
fr = fp	Z	Z

Z: High-impedance

Depending upon the VCO and LPF polarity, FC bit should be set.



Note: Give attention to the polarity for using active type LPF.

3. Power Saving Mode (Intermittent Mode Control Circuit)

Status	PS pin
Normal mode	Н
Power saving mode	L

The intermittent mode control circuit reduces the PLL power consumption.

By setting the PS pin low, the device enters into the power saving mode, reducing the current consumption. See the Electrical Characteristics chart for the specific value.

The phase detector output, Do, becomes high impedance.

For the dual PLL, the lock detector, LD, is as shown in the LD Output Logic table.

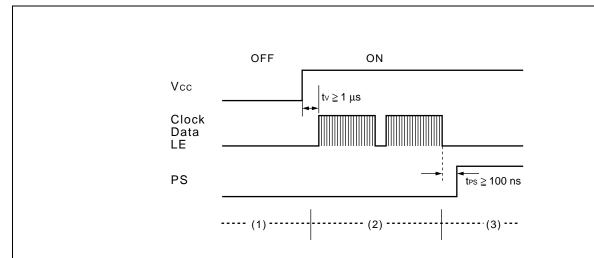
Setting the PS pin high, releases the power saving mode, and the device works normally.

The intermittent mode control circuit also ensures a smooth startup when the device returns to normal operation. When the PLL is returned to normal operation, the phase comparator output signal is unpredictable. This is because of the unknown relationship between the comparison frequency (fp) and the reference frequency (fr) which can cause a major change in the comparaor output, resulting in a VCO frequency jump and an increase in lockup time.

To prevent a major VCO frequency jump, the intermittent mode control circuit limits the magnitude of the error signal from the phase detector when it returns to normal operation.

Notes: • When power (VCC) is first applied, the device must be in standby mode.

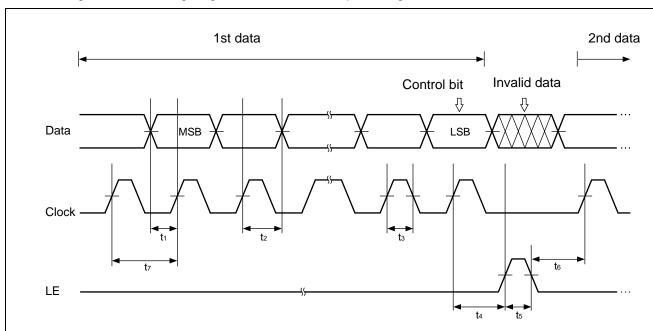
• PS pin must be set "L" at Power-ON.



- (1) PS = L (power saving mode) at Power-ON
- (2) Set serial data at least 1 μ s after the power supply becomes stable ($Vcc \ge 2.2 \text{ V}$).
- (3) Release power saving mode (PS_{IF,} PS_{RF}: "L" → "H") at least 100 ns later after setting serial data.

4. Serial Data Data Input Timing

Divide ratio is performed through a serial interface using the Data pin, Clock pin, and LE pin. Setting data is read into the shift register at the rise of the Clock signal, and transferred to a latch at the rise of the LE signal. The following diagram shows the data input timing.

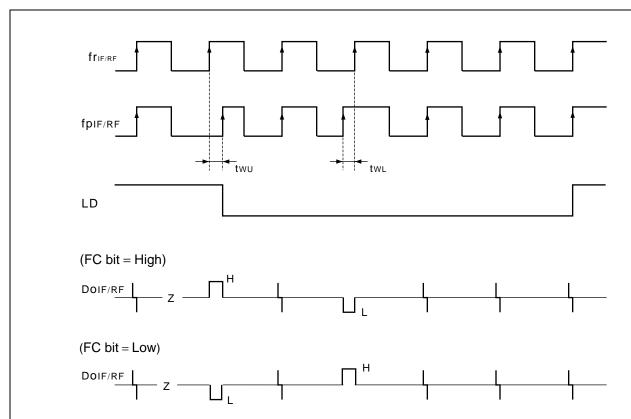


Parameter	Min	Тур	Max	Unit
t 1	20			ns
t 2	20	_	_	ns
t ₃	30		_	ns
t 4	30		_	ns

Parameter	Min	Тур	Max	Unit
t 5	100	_	_	ns
t ₆	20			ns
t 7	100			ns

Note: LE should be "L" when the data is transferred into the shift register.

■ PHASE COMPARATOR OUTPUT WAVEFORM



LD Output Logic

IF-PLL section	RF-PLL section	LD output	
Locking state/Power saving state	Locking state/Power saving state	Н	
Locking state/Power saving state	Unlocking state	L	
Unlocking state	Locking state/Power saving state	L	
Unlocking state	Unlocking state	L	

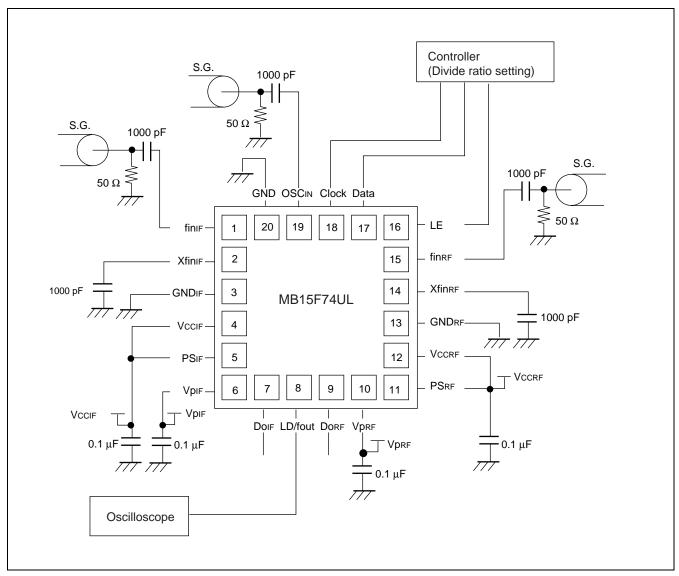
Notes : • Phase error detection range = -2π to $+2\pi$

- Pulses on DoiF/RF signals during locking state are output to prevent dead zone.
- LD output becomes low when phase error is two or more.
- LD output becomes high when phase error is twL or less and continues to be so for three cycles or more.
- two and two depend on OSC_{IN} input frequency as follows.

 $twu \ge 2/fosc$: e.g. $twu \ge 156.3$ ns when fosc = 12.8 MHz

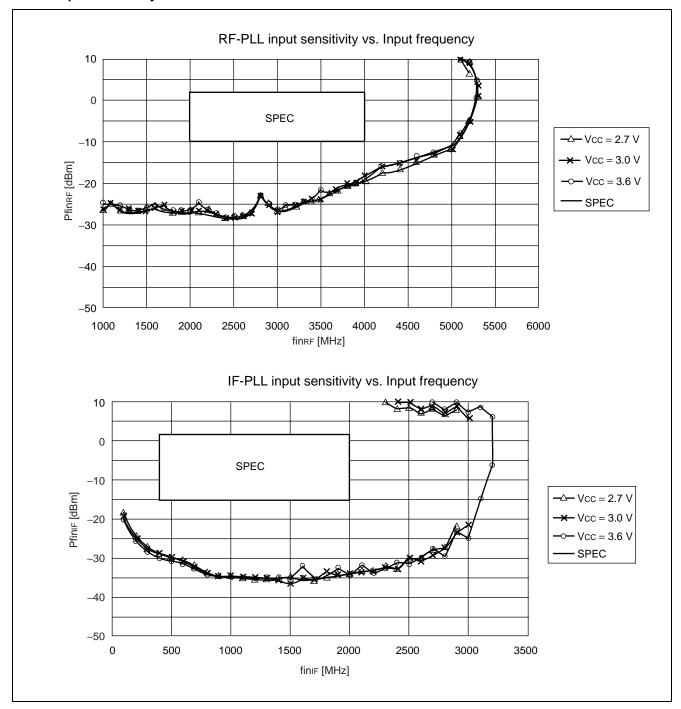
 $t_{WU} \le 4/fosc$: e.g. $t_{WL} \le 312.5$ ns when fosc = 12.8 MHz

■ TEST CIRCUIT (for Measuring Input Sensitivity fin/OSC_{IN})

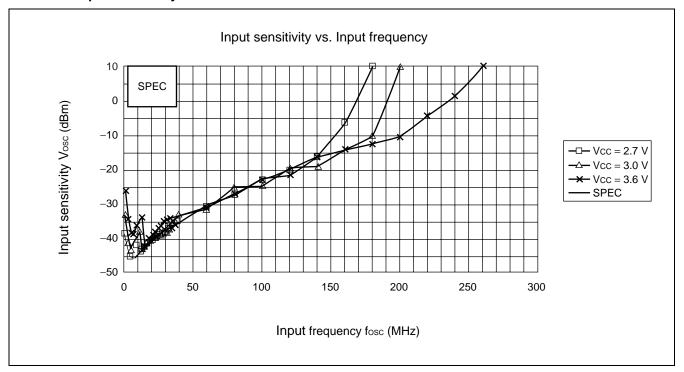


■ TYPICAL CHARACTERISTICS

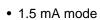
1. fin input sensitivity



2. OSC_{IN} input sensitivity

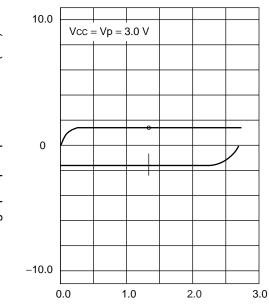


3. RF-PLL Do output current





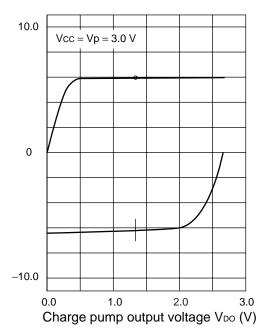
Charge pump output current loo (mA)



Charge pump output voltage V_{DO} (V)

• 6.0 mA mode



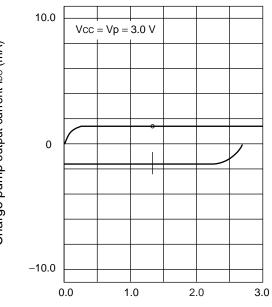


4. IF-PLL Do output current

• 1.5 mA mode

 $I_{\text{DO}} - V_{\text{DO}}$

Charge pump output current loo (mA)

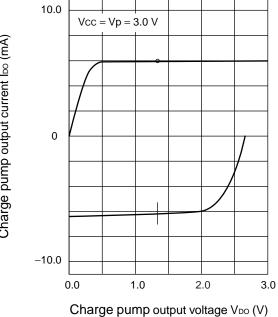


• 6.0 mA mode

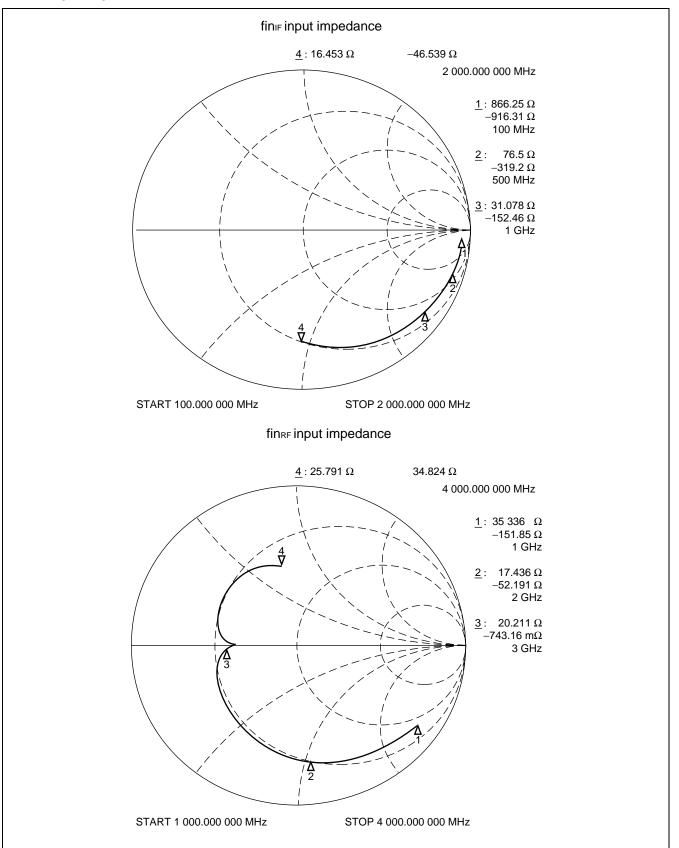
 $I_{DO} - V_{DO}$

Charge pump output voltage V_{DO} (V)

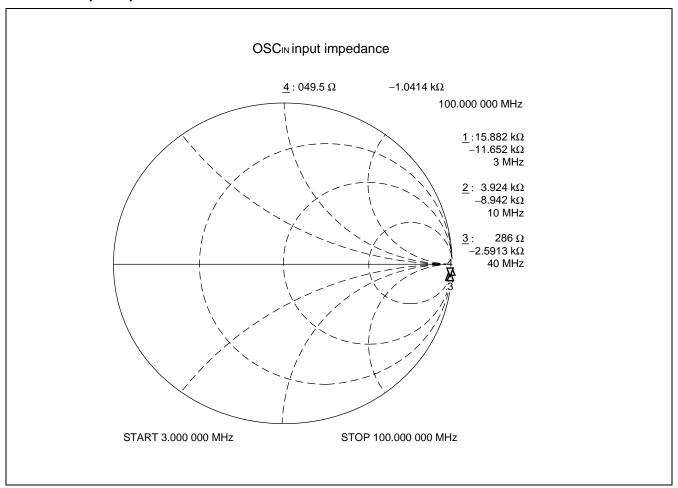




5. fin input impedance

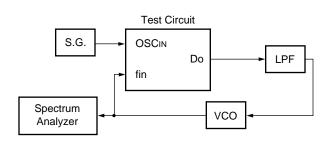


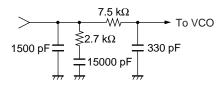
6. OSC_{IN} input impedance



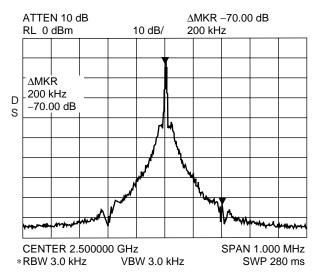
■ REFERENCE INFORMATION

(for Lock-up Time, Phase Noise and Reference Leakage)

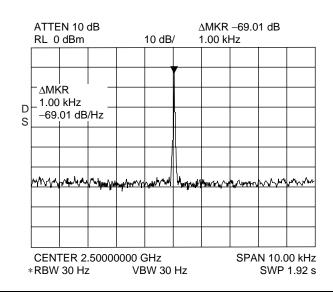




• PLL Reference Leakage

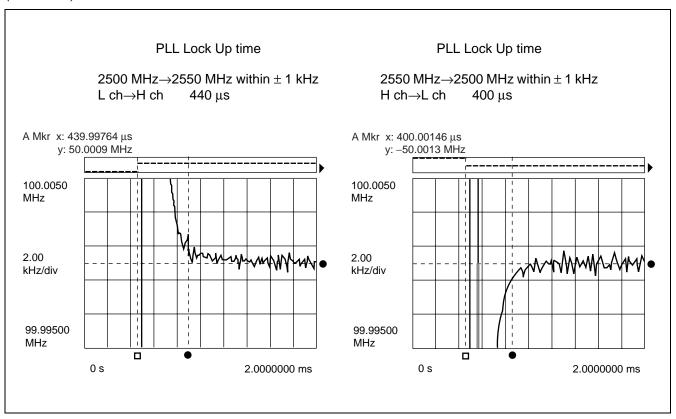


PLL Phase Noise

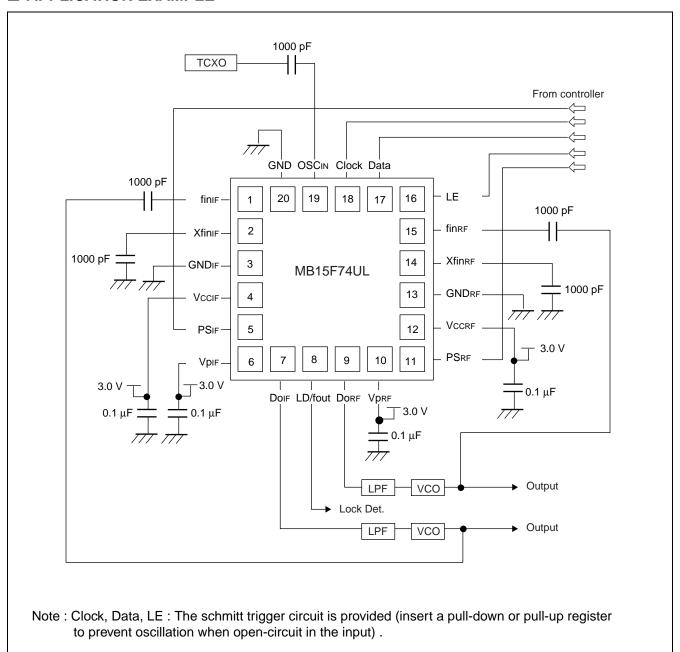


(Continued)

(Continued)



■ APPLICATION EXAMPLE



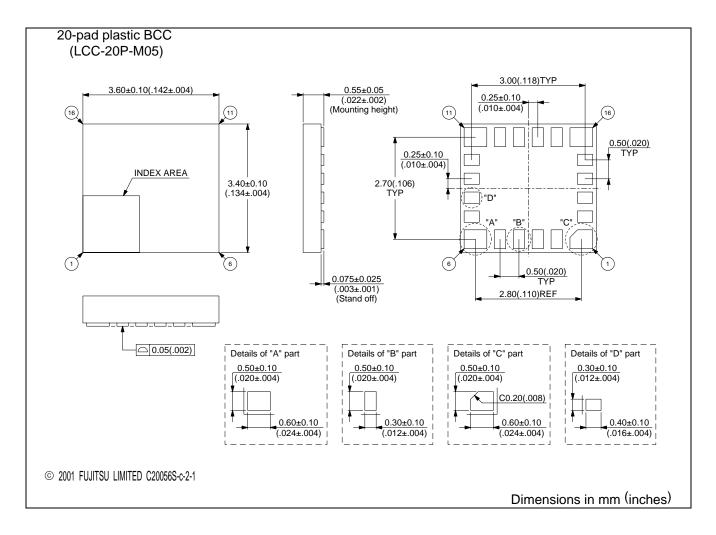
■ USAGE PRECAUTIONS

- (1) Vccrf, Vprf, Vccif and Vpif must be equal voltage. Even if either RF-PLL or IF-PLL is not used, power must be supplied to Vccrf, Vprf, Vccif and Vpif to keep them equal. It is recommended that the non-use PLL is controlled by power saving function.
- (2) To protect against damage by electrostatic discharge, note the following handling precautions:
 - Store and transport devices in conductive containers.
 - Use properly grounded workstations, tools, and equipment.
 - Turn off power before inserting or removing this device into or from a socket.
 - Protect leads with conductive sheet, when transporting a board mounted device

■ ORDERING INFORMATION

Part number	Package	Remarks
MB15F74ULPVA	20-pad plastic BCC (LCC-20P-M05)	

■ PACKAGE DIMENSION



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